

LOW NOISE LOW POWER TRANSIMPEDANCE AMPLIFIER IN 0.18 μ M CMOS TECHNOLOGY

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ABSTRACT

Low noise and low Power transimpedance amplifiers (TIA) are essential modules for optical sensor based systems. But low power and low noise TIAs are still a challenge for the scientists despite of rapid advances in complementary metal oxide semiconductor (CMOS) technology. This paper proposes a three-stage nested miller compensated (NMC) based design of low noise low power transimpedance amplifier for stable wideband operation. The circuit is designed in the 0.18 μ m CMOS technology by using Mentor Graphics environment. The simulation results show that the proposed TIA can operate at frequency 20 KHz and produces an output of 1.4265V for ± 1.2 V input voltages dissipating only 2.9206 mW power at 27 $^{\circ}$ C temperature. The complete layout of the TIA is only 0.005 μ m². This shunt-feedback TIA can be a better choice for high-resolution, low-to mid frequency applications.

Keywords: CMOS, low power, Opamp, TIA

1. INTRODUCTION

The current trend of all modern devices is to make it small, portable and cost-effective [1-5]. As a result the level of integration in all concurrent devices such as RFID, Bluetooth, Zigbee, Wi-Fi etc. has rapidly been increased, in last few years, due to the considerable advancement of CMOS technology [6-12]. Therefore, the prospect for integration of RF/digital/analogue circuits on a single chip becomes feasible and economical. As a result both individual and industry are becoming benefited [13-15].

A transimpedance amplifier (TIA) is a voltage amplifier that converts the current into a voltage. It is commonly used as shunt feedback path [16]. The ideal input has zero impedance, and the input signal is current. An output has low output impedance. Transimpedance amplifiers are commonly used in receivers for optical sensor based communication devices specially in preamplifier circuits [17]. The current generated by a photodetector causes a photo voltage in a nonlinear fashion and therefore, the amplifier has to prevent any large voltage by its low input impedance and generate either a 50 Ohm signal to drive a coaxial cable or a voltage signal for further amplification. Several fundamental structures of such amplifiers are available for different kinds of applications. The amplifiers have gained

preponderance over other linear amplifiers for low power and low voltage applications [18]. A low noise operational amplifier is suppose to have application oriented optimized performance [19].

Design of a high performance transimpedance amplifier is still a challenge for the sensor designers. For sensors that uses shunt feedback photo detectors should have a low noise, low power, high gain, fast settling and wide bandwidth amplifier [20, 21]. To achieve a best trade-off among these parameters, different researchers proposed several design compensation [20, 22-24]. The basic shunt-feedback topology uses a voltage amplifier with a feedback network that has the potential of obtaining lower overall input referred noise by optimizing the transistor sizes and aspect ratios in the amplifier's input stage [16].

This paper proposes low power design of a three stage Nested Miller compensation based transimpedance amplifier for the applications where low noise and stable wide band operation is the requirements. The circuit is designed in the 0.18 μ m CMOS technology by using Mentor Graphics environment. The simulation results confirm that the proposed TIA can be the best choice for low power optical sensor based communication receivers.

2. SHUNT-FEEDBACK TOPOLOGY

The basic shunt feedback topology, as shown in figure 1, usually uses a feedback loop network with the voltage amplifier to achieve wide band tuning. Such a structure can degrade the noise performance and it leads to a balance between sensitivity and bandwidth. It also reduces the DC voltage gain of the circuit. In the case of shunt feedback TIA, as an alternative, using the voltage gain control (CVG) and bootstrapping circuits are recommended to improve the bandwidth and to eliminate the signal swing from the photodiode. In addition, it also allows CVG shunt feedback TIA to handle the signal with soft edges and sharp transitions without affecting the transimpedance bandwidth.

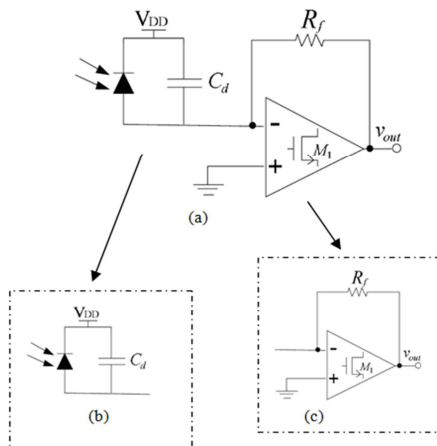


Figure 1. (a) The basic shunt feedback TIA (b) Photodiode (c) Network feedback (TIA)

3. NMC VOLTAGE AMPLIFIER OF THREE STAGE

In this paper, a three stage NMC based feedback network for shunt-feedback TIA is proposed. The schematic of the three-stage NMC based amplifier is shown in Fig. 2. The voltage amplifier is made up of two complementary differential gain stages (M1–M5 and M6–M9) and a final common-source gain stage (M10–M11). The compensation network includes, other than capacitors Cc1 and Cc2, a single nulling resistor Rc to eliminate the right-half-plane (RHP) zero. The NMC amplifier design approach is based on the design procedures used in [25] and [26]. The additional circuit design techniques are summarized in the subsequent paragraphs.

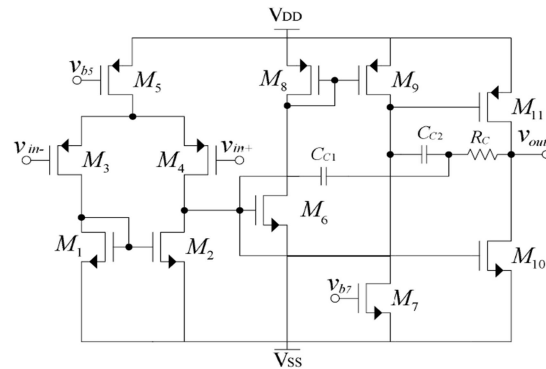


Figure 2. Schematic of three-stage NMC amplifier[25][26]

To maximize the slew rate (SR) and gain bandwidth, a p-channel input pair is required at the input stage to compensate the output noise caused by flicker noise. But the main problem is the increase in thermal noise because of less carrier mobility of p-channel transistors compared to their n-channel counterparts. Maximizing the bias current can help to overcome this drawback where input pair (M3, M4) maintains high aspect ratio and large sizes.

The output of the first differential amplifier connected to the gate M10 improves SR performance by providing a pseudo class AB output stage. As a result, output stage has much higher current when it drives a load capacitor than the current flowing through the output with no load. Compensation network is made up of a nulling resistor Rc. At higher frequencies, this compensation network moves the RHP to zero by achieving stability with minimum values of compensation capacitors (Cc1 and Cc2) with NMC amplifier.

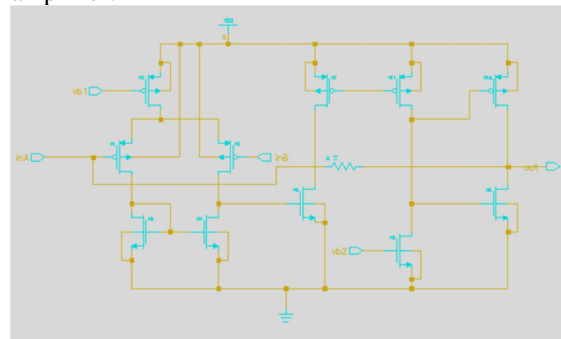


Figure 3. Schematic of proposed three-stage NMC amplifier

The schematic circuit of the proposed three stage NMC based TIA is shown in figure 3. In this design, optimization of the W/L ratio of the transistors has been used to achieve the better output results. The voltage amplifier is made up of two complementary differential gain stages (M1-

M5) and (M6-M9) and final common-source gain stage (M10-M11). However, other compensation networks including R_c , C_{c1} & C_{c2} in are omitted for the proposed design. The aspect ratios of the width and length of the transistor are shown in Table 1.

Table 1: Transistors Ratio W/L (μm).

Transistor	Aspect Ratio (μm)
M1, M2	0.5 / 0.18
M3, M4	0.6 / 0.18
M5	0.65 / 0.18
M6, M7	1.4 / 0.18
M8, M9	0.65 / 0.18
M10	22.5 / 0.18
M11	12.5 / 0.18

While the input noise components of the basic shunt-feedback TIA originate mainly from the thermal noise of feedback resistor, R_f , and the input referred noise of the voltage amplifier. At low frequencies, the input noise is dominated by the feedback resistor's thermal noise. But at higher frequencies and for sufficiently high loop gain A_0 , the input referred noise of the voltage amplifier may become dominant [16]. In the proposed TIA, the input noise and the bandwidth are dependent on the feedback resistor R_f . For applications like Photodiode based sensors, large TIA gain is required. While increasing the value of R_f can cause a decrease in the input noise contribution and an increase in the TIA transimpedance gain.

4. RESULTS AND DISCUSSIONS

The proposed TIA has been designed in 0.18 μm CMOS process using the Mentor Graphics software environment. The properties of input and output voltages used in the simulation are described in table 2. The simulation result of three stage NMC voltage amplifier is shown in Fig. 4. Both the input voltages $V(\text{inA})$ and $V(\text{inB})$ of the amplifier are $\pm 1.2\text{ V}$ and the output is 1.4265V. Total power dissipation is 2.9206 mW. The operational frequency of TIA is 20 KHz.

Table 2: Characteristics of input and output voltages.

Parameter	NMC Amplifier	
	V(inA/inB)	V(out)
Voltage(V)	V(inA/inB)	V(out)
Pulse width (μs)	21.000	20.855
Risetime (ns)	800	799.97
Settle Time (μs)	72.950	72.938
Fall time (ns)	800	792.36
Maximum Voltage(V)	± 1.2	1.4265
Voltage(V)	V(inA/inB)	V(out)

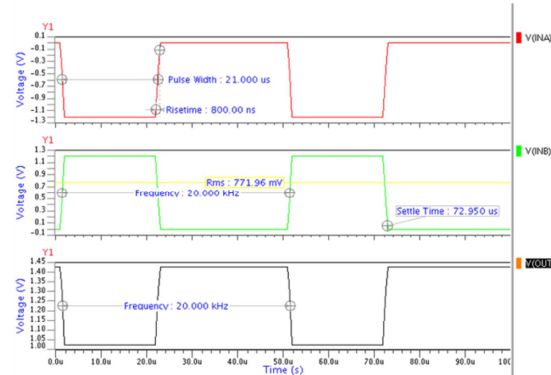


Figure 4. Input and output waveforms of TIA

It should be noted that in case of soft-edged waveforms, the first operating mode of the TIA is preferred to reduce the DC and lower frequency components. On the other hand, in the case of sharp-edged waveforms, the second operating mode of the TIA is required for its appropriate function. The test bench set up for proposed TIA is given in table 3.

Table 3: Test bench set up for TIA.

Parameter	TestBench	
	V(inA)	V(inB)
Voltage(V)	V(inA)	V(inB)
Initial	0	0
Pulse(V)	-1.2	1.2
Delay (μs)	1us	1us
Rise (μs)	1	1
Fall (μs)	1	1
Width (μs)	20	20
Period (μs)	50	50

RMS Noise performance of the proposed TIA is shown in figure 5. Information of RMS noise value describe in table 4.

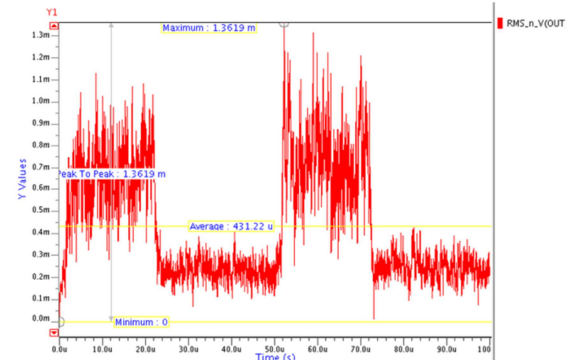


Figure 5. RMS Noise of Output

Table 4: RMS Noise measurement data.

Noise	RMS
Maximum	1.3619m
Peak to Peak	1.3619m
Average	431.22 μ
Minimum	0

Complete layout of the proposed TIA is shown in figure 6. IC design tools of mentor graphics is used to design the layout. Total size of the chip is $0.005 \mu\text{m}^2$.

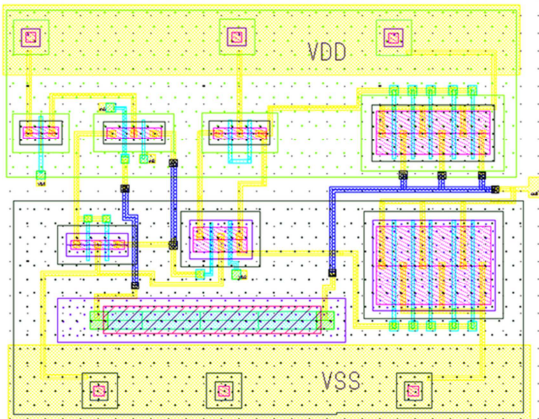


Figure 6. Complete layout of the proposed TIA

5. CONCLUSION

In an optical sensor based communication device, a high-performance transimpedance amplifier is an essential module. In this paper, a three stage operational amplifiers have been designed in $0.18\mu\text{m}$ CMOS process technology based on NMC technique to improve the power and noise performances. Total power dissipation is 2.9206 mW at input voltages of $\pm 1.2 \text{ V}$ which is very low. The total dimension of the proposed TIA is only $0.005 \mu\text{m}^2$. Such an amplifier will be the best choice for low power, low noise low-to mid frequency SOC applications.

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